

Form PTO-1449

Document Number (Optional)

Application Number

MEG-02-005

10/786,807

Applicant

H.M. Chen et al.

Filing Date

02/25/04

Group Art Unit

**INFORMATION DISCLOSURE CITATION
IN AN APPLICATION**

(Use several sheets if necessary)

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILED DATE IF APPROPRIATE
	62912689	1/18/01	Ho	438	108	1/18/01
	6162652	12/19/00	Dass et al.	438	18	12/31/97
	6143668	11/7/00	Dass et al.	438	763	9/30/97

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

EXAMINER

Ben Hu

DATE CONSIDERED

7/25/05

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

MEG-02-005

U.S. Patent 6,291,268 to Ho, "Low Cost Method of Testing a Cavity-Up BGA Substrate," discloses a method for testing a BGA substrate.

U.S. Patent 6,162,652 to Dass et al., "Process for Sort Testing C4 Bumped Wafers," describes a method of cleaning and testing bumped wafers.

U.S. Patent 6,143,668 to Dass et al., "KLXX Technology with Integrated Passivation Process, Probe Geometry and Probing Process," describes a wafer testing method utilizing cleaning of bond pads prior to testing.

Sincerely,

A handwritten signature in black ink, appearing to read 'SBA', with a stylized flourish extending from the end.

Stephen B. Ackerman,
Reg. No. 37761